

L Number	Hits	Search Text	DB	Time stamp
1	0	laser adj2 chip\$1 and cool\$3 adj2 element and chip adj2 mount\$3 adj2 area and (divid\$3 or cut\$3)	USPAT; EPO; JPO; DERWENT	2004/07/27 15:54
2	15	laser adj2 chip\$1 and cool\$3 adj2 element and solder\$3 and (divid\$3 or cut\$3)	USPAT; EPO; JPO; DERWENT	2004/07/27 16:12
3	57	laser adj2 chip\$1 and heat adj2 sink and ceramic and (divid\$3 or cut\$3)	USPAT; EPO; JPO; DERWENT	2004/07/27 16:14
4	53	(laser adj2 chip\$1 and heat adj2 sink and ceramic and (divid\$3 or cut\$3)) not (laser adj2 chip\$1 and cool\$3 adj2 element and solder\$3 and (divid\$3 or cut\$3))	USPAT; EPO; JPO; DERWENT	2004/07/27 16:13
5	0	laser adj2 chip\$1 and heat adj2 sink and ceramic and (divid\$3 or cut\$3) and chip adj2 mount\$3 adj2 area	USPAT; EPO; JPO; DERWENT	2004/07/27 16:15
6	0	laser adj2 chip\$1 and heat adj2 sink and ceramic and (divid\$3 or cut\$3) and chip near5 mount\$3 adj2 area	USPAT; EPO; JPO; DERWENT	2004/07/27 16:15
7	1	laser adj2 chip\$1 and heat adj2 sink and ceramic and (divid\$3 or cut\$3) and chip near5 mount\$3 near5 area	USPAT; EPO; JPO; DERWENT	2004/07/27 16:23
8	5	laser adj2 chip\$1 and heat adj2 sink and (divid\$3 or cut\$3) and (plate or carrier) and chip near5 mount\$3 near5 area	USPAT; EPO; JPO; DERWENT	2004/07/27 16:25
9	5	laser adj2 chip\$1 and ((heat adj2 sink) or cooling) and (divid\$3 or cut\$3) and (plate or carrier) and chip near5 mount\$3 near5 area	USPAT; EPO; JPO; DERWENT	2004/07/27 16:25